

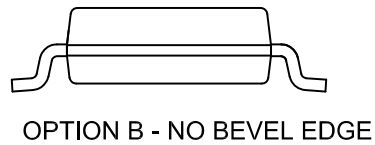
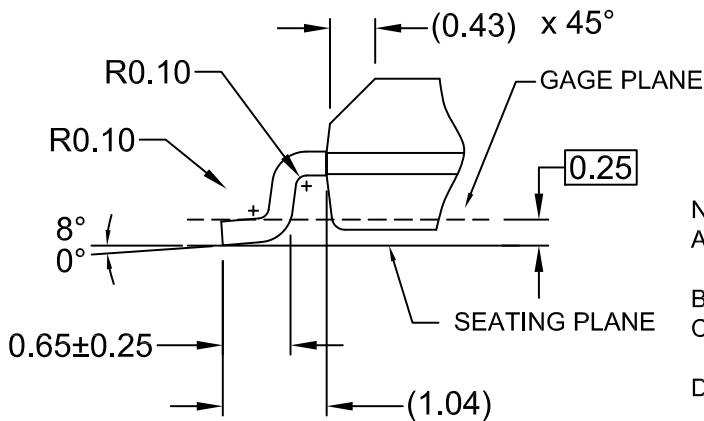
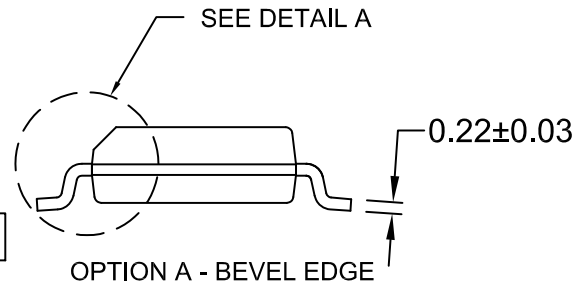
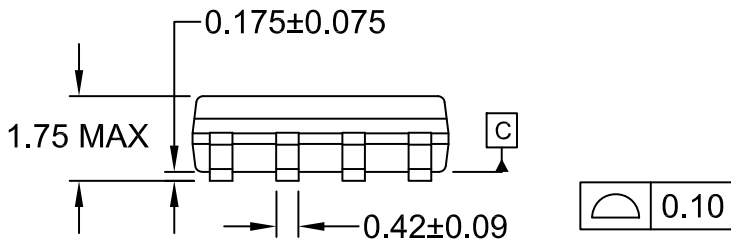
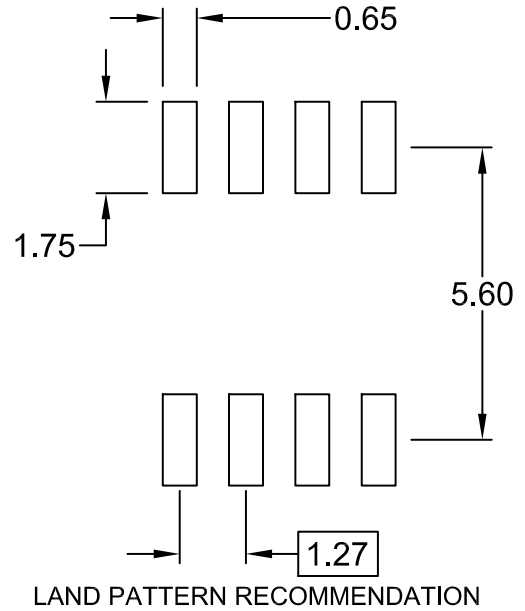
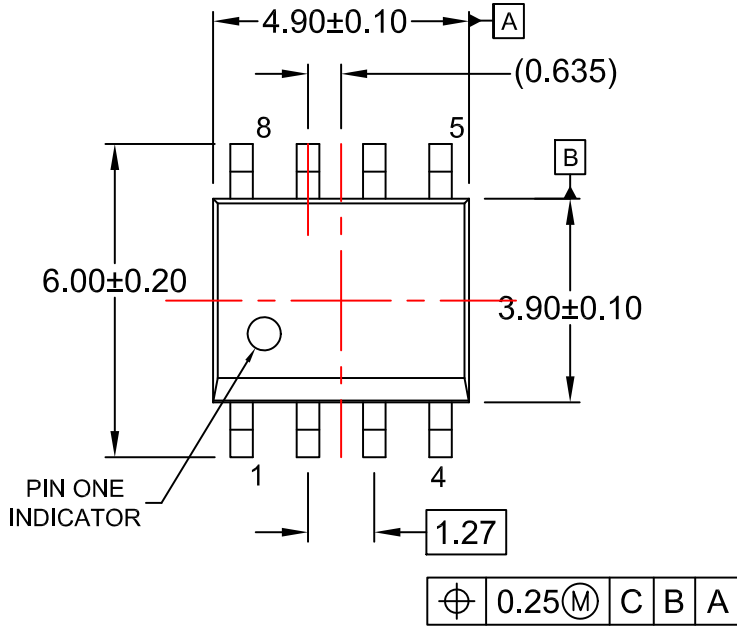
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®



SOIC8
CASE 751EB
ISSUE A

DATE 24 AUG 2017



- NOTES:
- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AA.
 - B) ALL DIMENSIONS ARE IN MILLIMETERS.
 - C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.
 - D) LANDPATTERN STANDARD: SOIC127P600X175-8M

DETAIL A
 SCALE: 2:1

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|-------------------------|----------------------------------|--|
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| STATUS: | ON SEMICONDUCTOR STANDARD | |
| NEW STANDARD: | | |
| DESCRIPTION: | SOIC8 | PAGE 1 OF 2 |

